

ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH SUBSTRATE AND METHOD OF MANUFACTURE THEREOF

An integrated circuit packaging system and method of manufacture thereof includes: a substrate having a top insulation layer and a top conductive layer; an inter-react layer on the substrate; an integrated circuit die on the substrate; a package body on the inter-react layer and the integrated circuit die; and a top solder bump on the top conductive layer, the top solder bump in a 3D via formed through the package body, the inter-react layer, and the top insulation layer for exposing the top conductive layer in the 3D via.

(Fig.2)